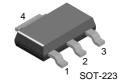


## MPSA27/PZTA27

# **NPN General Purpose Amplifier**

- This device is designed for applications requiring extremely high current gain at collector currents to 500mA.
- Sourced from process 03.
- See MPSA28 for characteristics.





1. Emitter 2. Base 3. Collector

1. Base 2. Collector 3. Emitter

## Absolute Maximum Ratings\* T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Value	Units
V <sub>CES</sub>	Collector-Emitter Voltage	4	60	V
V <sub>CBO</sub>	Collector-Base Voltage	15 173	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	2	10	V
I <sub>C</sub>	Collector current - Continuous		800	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature		-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- NOTES:
  1) These ratings are based on maximum junction temperature of 150 degrees C.
  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# Electrical Characteristics T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Characte	Off Characteristics						
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage	$I_C = 100 \mu A, V_{BE} = 0$	60			V	
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10\mu A, I_C = 0$	60			V	
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_C = 100 \mu A, I_C = 0$	10			V	
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 50V, I_{E} = 0$			100	nA	
I <sub>CES</sub>	Collector Cutoff Current	$V_{CE} = 50V, V_{BE} = 0$			500	nA	
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 10V, I_{C} = 0$			100	nA	
On Characte	On Characteristics						
h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 5.0V I <sub>C</sub> = 100mA, V <sub>CE</sub> = 5.0V	10000 10000				
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 100 \text{mA}, I_B = 0.1 \text{mA}$			1.5	V	
V <sub>BE(on)</sub>	Base-Emitter On Voltage	$I_C = 100 \text{mA}, V_{CE} = 5.0 \text{V}$			2.0	V	
Small Signal Characteristics							
f <sub>T</sub>	Current Gain Bandwidth Product	$I_C = 10$ mA, $V_{CE} = 5.0$ V, $f = 100$ MHz	125			MHz	

## Thermal Characteristics T<sub>A</sub>=25°C unless otherwise noted

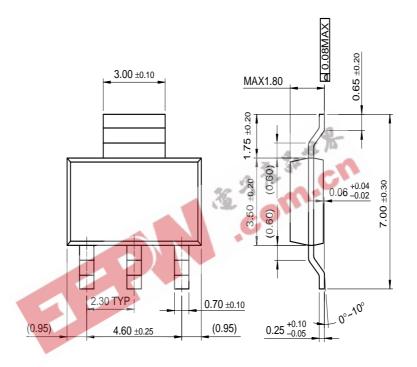
Symbol	Parameter	M	Lluita	
		MPSA27	*PZTA27	Units
P <sub>D</sub>	Total Device Dissipation	625	1000	mW
	Derate above 25°C	5.0	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	125	°C/W
	n FR-4 PCB 36mm × 18mm × 1.5mm; mounting pad for the collector lead min.	6cm.		

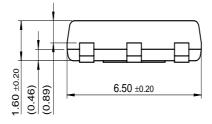
©2002 Fairchild Semiconductor Corporation

# **Package Dimensions** TO-92 $4.58^{\,+0.25}_{\,-0.15}$ 4.58 ±0.20 14.47 ±0.40 $0.46 \pm 0.10$ 1.27TYP [1.27 ±0.20] $0.38^{\,+0.10}_{\,-0.05}$ 1.27TYP [1.27 ±0.20] 3.60 ±0.20 (0.25)1.02 ±0.10 0.38 +0.10 (R2.29) Dimensions in Millimeters

# Package Demensions (Continued)

# **SOT-223**





Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench <sup>®</sup>	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	$QS^{TM}$	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E <sup>2</sup> CMOS <sup>TM</sup>	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I <sup>2</sup> C <sup>TM</sup>	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	$VCX^{TM}$
Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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Rev. I1

## **PRODUCT STATUS DEFINITIONS**

### **Definition of Terms**

Datasheet Identification	Product Status	Definition
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